CLAIMS

What is claimed is:

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- 1. A method for underfilling an electronic chip mounted on a substrate, said method comprising:
- a. dispensing underfill on said substrate
- dipping said chip in a tacky thermosettable flux that does not contain filler to create a dipped chip,
 - c. placing said dipped chip on said substrate covered with underfill,
 - d. soldering said dipped chip to said substrate, and
 - e. curing said underfill.

2. The method of claim 1 in which all or some of said steps are performed by a machine.

3. The method of claim 1 in which all or some of said steps are performed manually.

- 4. The method of claim 1 wherein said underfill is filled.
- 5. The method of claim 1 wherein said underfill is not filled.

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6. The method of claim 1 wherein said flux has a viscosity approximately 1 - 100,000 times greater than that of said underfill.

- 7. The method of claim 6 wherein said flux has a viscosity 1 100 times greater than that of said underfill.
- 8. The method of claim 7 wherein said flux has a viscosity 3 60 times greater than that of said underfill.
 - 9. The method of claim 1 wherein said steps a and b are reversed.
- 10 10. The method of claim 1 wherein said steps d and e are conducted simultaneously.
 - 11. A process for connecting an integrated circuit chip to a substrate comprising
 - a. coating the connection area of said substrate with an underfill,
 - b. dipping said chip into a tacky thermosettable flux so that the connection bumps of said chip are coated with said flux,
- c. placing said chip having said flux onto said substrate so
 that the bumps of said chip are in contact with the pads of said substrate,
 - d. soldering said chip to said substrate, and
 - e. curing said underfill.

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- 12. The method of claim 11 wherein said steps a and b are reversed.
- 13. The method of claim 11 wherein said steps d and e are conducted simultaneously.